

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10722174			
<b>Filing Date:</b>	25-Nov-2003			
<b>Title of Invention:</b>	On-wafer electrochemical deposition plating metrology process and apparatus			
<b>First Named Inventor/Applicant Name:</b>	MacKenzie King			
<b>Filer:</b>	Steven John Hultquist			
<b>Attorney Docket Number:</b>	ATMI-688			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
Claims in excess of 20	1202	2	50	100
Independent claims in excess of 3	1201	1	210	210
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
Extension - 3 months with \$120 paid	1253	1	930	930
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	810	810
<b>Total in USD (\$)</b>				<b>2050</b>